Diodes Inc. Material Data Sheet
Rev: May 2009

SBR10100CTFP SBR10150CTFP SBR10200CTFP SBR1040CTFP SBR1060CTFP SBR10U100CTFP SBR10U150CTFP SBR10U200CTFP SBR10U300CTFP SBR10U40CTFP SBR10U60CTFP SBR20100CTFP SBR20150CTFP SBR2040CTFP SBR2045CTFP SBR2060CTFP SBR20A100CTFP SBR20A120CTFP SBR20A150CTFP SBR20A200CTFP SBR20A300CTFP SBR20A40CTFP SBR20A45CTFP SBR20A60CTFP SBR20U100CTFP SBR20U150CTFP SBR20U40CTFP SBR20U60CTFP SBR30100CTFP SBR30150CTFP SBR30200CTFP SBR30300CTFP SBR3040CTFP SBR3045CTFP SBR3060CTFP SBR30A100CTFP SBR30A120CTFP SBR30A150CTFP SBR30A40CTFP SBR30A45CTFP SBR30A60CTFP SBR30M100CTFP SBR40100CTFP SBR40150CTFP SBR4040CTFP SBR4045CTFP SBR4060CTFP

Part Number: **SBR ITO-220**
Weight (mg): 1832.718

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Si, Doped	7440-21-3	100.00%	0.74	13.5	1000000	7366
Leadframe & Clip	C1220	Copper	7440-50-8	99.81%	39.09	716.5	998100	390207
		Fe	7439-89-6	0.10%			1000	391
		Phosphorus	7723-14-0	0.03%			300	117
		Silver	7740-22-4	0.03%			300	117
		Nickel(All)	7440-02-0	0.03%			300	117
Encapsulation	EK3600T	Silica Fused	60676-86-0	75.00%	58.79	1077.5	750000	440943
		Epoxy Resin	29690-82-2	15.00%			150000	88189
		Phenolic Resin	9003-35-4	7.00%			70000	41155
		Antimony Trioxide	N/A	3.00%			30000	17638
Bonding Wire	15 mil Wire	Al	7429-90-5	100.00%	0.67	12.248	1000000	6683
Die Attach Solder	PbSnAg Solder	Lead	7439-92-1	92.50%	0.34	6.3	925000	3180
		Tin	7440-31-5	5.00%			50000	172
		Silver	7740-22-4	2.50%			25000	86
Lead Plating Finish	Tin Solder	Sn (>99.5%)	7440-31-5	100.00%	0.36	6.67	1000000	3639
				Total	100.00	1832.72		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

***** The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

RoHS Exemption7a for Pb in High Temperature, High %Pb in Solder applied